

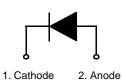
## **Ultrafast Rectifier**

# FFPF10UP60S

## **Features**

- Ultrafast with soft recovery (@ I<sub>F</sub> = 1A), < 40ns</li>
- Reverse Voltage, 600V
- Forward Voltage (@  $T_C = 60^{\circ}C$ ), < 2V
- Enhanced Avalanche Energy

# TO-220F-2L



## **Applications**

- General purpose
- Switching mode power supply
- · Free-wheeling diode for motor application
- Power switching circuits

# Absolute Maximum Ratings T<sub>C</sub>=25°C unless otherwise noted

Symbol	Parameter	Value	Units
V <sub>RRM</sub>	Peak Repetitive Reverse Voltage	600	V
I <sub>F(AV)</sub>	Average Rectified Forward Current @ T <sub>C</sub> = 60°C	10	Α
I <sub>FSM</sub>	Non-repetitive Peak Surge Current 60Hz Single Half-Sine Wave	50	Α
T <sub>J,</sub> T <sub>STG</sub>	Operating Junction and Storage Temperature	- 65 to +150	°C

## **Thermal Characteristics**

Symbol	Parameter	Value	Units
$R_{\theta JC}$	Maximum Thermal Resistance, Junction to Case	4.5	°C/W

## Electrical Characteristics T<sub>C</sub>=25 °C unless otherwise noted

Symbol	Parameter		Min.	Тур.	Max.	Units
V <sub>FM</sub> *	Maximum Instantaneous Forward Voltage					V
	I <sub>F</sub> = 10A	$T_{C} = 25  ^{\circ}\text{C}$ $T_{C} = 100  ^{\circ}\text{C}$	-	-	2.2	
	I <sub>F</sub> = 10A	T <sub>C</sub> = 100 °C	-	-	2.0	
I <sub>RM</sub> *	Maximum Instantaneous Reverse Current					μΑ
	@ rated V <sub>R</sub>	$T_C = 25  ^{\circ}C$ $T_C = 100  ^{\circ}C$	-	-	100	
		T <sub>C</sub> = 100 °C	-	-	500	
t <sub>rr</sub>	Reverse Recovery Time		-	34	40	ns
I <sub>rr</sub>	Reverse Recovery Current		-	1.0	1.5	Α
Q <sub>rr</sub>	Reverse Recovery Charge		-	17	30	nC
	$(I_F = 1A, di/dt = 100A/\mu s)$					
t <sub>rr</sub>	Maximum Reverse Recovery Time		-	58	-	ns
	$(I_F = 10A, di/dt = 200A/\mu s)$					
W <sub>AVL</sub>	Avalanche Energy (L=40mH)		20	-	-	mJ

<sup>\*</sup> Pulse Test: Pulse Width=300µs, Duty Cycle=2%

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# **Typical Characteristics**

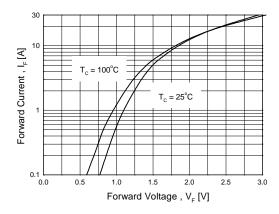


Figure 1. Typical Forward Voltage Drop vs. Forward Current

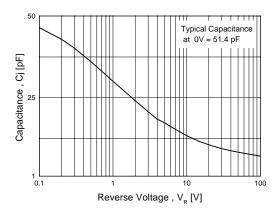


Figure 3. Typical Junction Capacitance

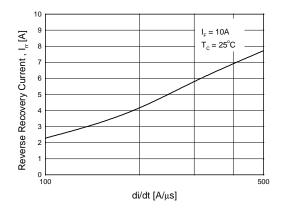


Figure 5. Typical Reverse Recovery Current vs. di/dt

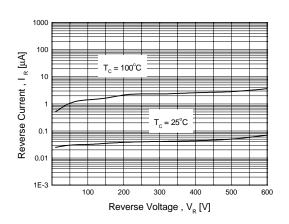


Figure 2. Typical Reverse Current vs. Reverse Voltage

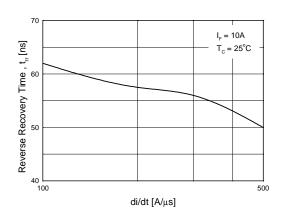


Figure 4. Typical Reverse Recovery Time vs. di/dt

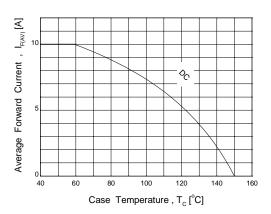


Figure 6. Forward Current Derating Curve

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# **Package Dimensions** TO-220F-2L 10.16 ±0.20 $\emptyset 3.18 \pm 0.10$ 2.54 ±0.20 3.30 ±0.10 (0.70)6.68 ±0.20 0 0 (1.00x45°) 15.80 ±0.20 **1**(1.80) (6.50) $9.75 \pm 0.30$ MAX1.47 2.76 ±0.20 0.80 ±0.10 0.35 ±0.10 2.54TYP 2.54TYP [2.54 ±0.20] [2.54 ±0.20] 0.50 +0.10 -0.05 $4.70 \pm 0.20$ $9.40 \pm 0.20$ Dimensions in Millimeters

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EnSigna™	i-Lo™	OCX™	RapidConnect™	UHC™
FACT™	ImpliedDisconnect™	OCXPro™	μSerDes™	UltraFET <sup>®</sup>
FACT Quiet series™		OPTOLOGIC <sup>®</sup>	SILENT SWITCHER®	VCX™
Across the board. Around the world.™		OPTOPLANAR™	SMART START™	
The Power Franchise®		PACMAN™	SPM™	
Programmable Active Droop™		POP™	Stealth™	
3				

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